

UP SuperServer SYS-111C-NR



More details here

Key Applications

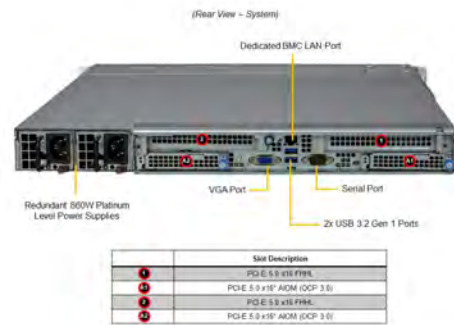
Virtualization, HPC, CDN, Edge Nodes, Cloud Computing, Data Center
Optimized, Storage Headnode,

Key Features

- Single Socket E (LGA-4677) 4th Gen Intel® Xeon® Scalable processors. Up to 350W TDP;
- Intel® C741 Chipset;
- 16 DIMMs; Supports 3DS DDR5 RDIMM. Up to 4800 MT/s;
- 2 PCIe 5.0 x16 FHHL; 2 PCIe 5.0 x16 AIOM NIC(OCP 3.0); 2 PCIe 3.0 x2 NVMe M.2;
- Dual AIOM (OCP 3.0) for networking (NCSI available), 1 dedicated IPMI LAN;
- 10x front hot-swap 2.5" SATA3 drive bays (Optional all 10 hybrid Gen5 NVMe), SAS3 with additional SAS controller card;
- Redundant Platinum 860W Power Supplies;



Form Factor	1U Rackmount Enclosure: 437 x 43 x 597mm (17.2" x 1.7" x 23.5") Package: 602 x 195.6 x 807.7mm (23.7" x 7.7" x 31.8")
Processor	4th Gen Intel® Xeon® Scalable processors Single Socket LGA 4677 (Socket E) supported (Supports up to 350W TDP CPUs (Aircooled), CPUs (air cooled) with TDP over 300W are only supported under specific conditions. Contact customer support for details.)
System Memory	16 DIMM slots
Drive Bays	10x 2.5" NVMe/SATA/SAS drive bays; 10x 2.5" NVMe hybrid;
Expansion Slots	2 PCIe 5.0 x16 FHHL slot(s) Note: AIOM slots share PCIe lanes with NVMe drives. Acronyms: (FH = Full Height, LP = Low Profile, FL = Full Length, HL = Half Length)
On-Board Devices	SATA: SATA3 (6Gbps); RAID 0/1/5/10 support NVMe: NVMe Chipset: Intel® C741 Network Connectivity: Via AIOM IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	SATA: 12 SATA (6Gbps) port(s) LAN: 1 RJ45 Dedicated IPMI LAN port USB: 2 USB 2.0 port(s) (2 front) 2 USB 3.2 Gen 1 port(s) (2 rear) Video: 1 VGA port(s) Serial Port: 1 COM Port(s) (1 COM)



System Cooling	6x (4cm x 4cm x 5.6cm) heavy duty fan(s)
Power Supply	800W/860W 1U redundant power supply Dimension (W x H x L): 54.5 x 40.25 x 322 mm Output Type: Backplanes (gold finger)
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
Management	NMI; SUM; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; Redfish API; IPMI2.0
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory 8 Phase-switching voltage regulator FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Height: 1.7" (43 mm) Width: 17.2" (437 mm) Depth: 23.5" (597 mm) Gross Weight: 40 lbs (18.14 kg) Net Weight: 25 lbs (11.34 kg) Packaging: 7.7" (H) x 23.7" (W) x 31.8" (D) Available Color: Black
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	Super X13SEDW-F
Chassis	CSE-LB16TS-R860AWP3